ocket No.: 060188-0594

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Customer Number: 20277

Shuji HIRAO

Confirmation Number: 6629

Application No.: 10/624,564

Group Art Unit: 1753

Filed: July 23, 2003

Examiner: WONG, Edna

For: METHOD AND APPARATUS FOR PLATING SUBSTRATE

RESPONSE TO RESTRICTION REQUIREMENT

Mail Stop Restriction Requirement Honorable Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

Noting the Office Action of March 24, 2006 wherein restriction has been required, Applicant hereby elects Group I (claims 1-11) for prosecution in the above-identified application.

To the extent necessary, a petition for an extension of time under 37 C.F.R. 1.136 is hereby made. Please charge any shortage in fees due in connection with the filing of this paper, including extension of time fees, to Deposit Account 500417 and please credit any excess fees to such deposit account.

Respectfully submitted,

McDERMOTT WILL & EMERY LLP

Michael E. Fogarty

Registration No. 36,139

Please recognize our Customer No. 20277

as our correspondence address.

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Facsimile: 202.756.8087 Date: April 24, 2006